

PATENT ABSTRACTS OF JAPAN

(11)Publication number : 09-097733

(43)Date of publication of application : 08.04.1997

(51)Int.Cl.

H01G 4/12
H01G 4/12
// H01G 13/00

(21)Application number : 07-276606

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(22)Date of filing : 29.09.1995

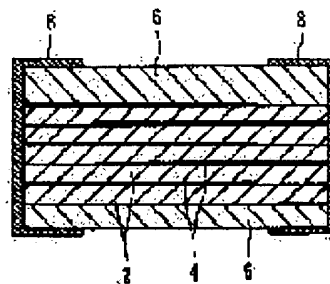
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(54) MANUFACTURE OF LAMINATED CERAMIC COMPONENT

(57)Abstract:

PROBLEM TO BE SOLVED: To hardly generate a delamination between dielectric layers and protective layers by a method wherein green sheets, whose shrinkage starting temperature due to a firing is lower than that of green sheets for the dielectric layers use, are used as green sheets for the protective layers use.

SOLUTION: A plurality of sheets of green sheets, which are respectively formed with an internal electrode pattern 4 consisting of a conductive paste and are ones for dielectric layers 2 use, are laminated on a green sheet in such a way that the patterns 4 oppose to each other holding the green sheets for the layers 2 use between them. Moreover, green sheets for protective layers 6 use are laminated on the upper and lower surfaces of this laminated material by several sheets and a large pressure is applied to the laminated material from the vertical directions to make these green sheets pressure bond. At this time, as the green sheets for the layers 6 use, green sheets, whose shrinkage starting temperature due to a firing is lower than that of the green sheets for the layers 2 use, are used and green sheets having a density higher than that of the green sheets for the layers 2 use are used. Thereby, a difference between the shrinkage behaviours of the green sheets for the layers 6 use and the green sheets for the layers 2 use at the time of the firing is decreased and as the internal stress of the laminated material is relaxed, the deformation of a product is reduced.



LEGAL STATUS

[Date of request for examination] 17.02.2000

[Date of sending the examiner's decision of rejection] 29.01.2002

[Kind of final disposal of application other than

the examiner's decision of rejection or
application converted registration]
[Date of final disposal for application]
[Patent number]
[Date of registration]
[Number of appeal against examiner's decision of
rejection]
[Date of requesting appeal against examiner's
decision of rejection]
[Date of extinction of right]

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